Electronic Supplementary Information

From garish to practical: synergetic effect of short-circuiting and chargetrapping for high-entropy energy harvesting

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Note S1. Output analysis of a contact-separation TENG

Intrinsic characteristics of transferred charge quantity (Q_{SC}) of contact-separation TENG is given as:¹

$$
Q_{sc} = \frac{S\sigma x_{(t)}}{d_0 + x_{(t)}}
$$

Where S, σ , d_0 and $x_{(t)}$ represent the surface of triboelectric layer, surface charge density, effective dielectric thickness, and the distance between the triboelectric layers, respectively. The correlation between transferred charge quantity and total triboelectric charge can be derived by dividing the numerator and denominator by $x_{(t)}$:

$$
\frac{Q_{sc}}{S\sigma} = \frac{1}{\frac{d_0}{x_{(t)}} + 1}
$$

Which is less than unity, indicating reduced transferred charge.

Note S2. Multiphysics simulation parameters

In using the COMOSOL simulations to analyze the potential distribution of HEEH, we applied Gauss's law (integral form):

$$
\int \partial V \ dA(n.E) = \frac{1}{\varepsilon_0 \varepsilon_r} \int V \ dV \rho \tag{1}
$$

we have the following assumption:

- 1. The triboelectrification area is infinitely large because the size of the triboelectrification layer and electrode layer is substantially larger than their thickness.
- 2. The inner electric field inner is uniform.

For the raw device, we have the following:

$$
\int top \ dxdyz. zE(z) + \int bottom \ dxdy(-z) \cdot (-zE(z)) = \frac{1}{\varepsilon_0} \int V \ dV \rho
$$
\n
$$
EA_{top} + EA_{bottom} = 2E(z)A = \frac{1}{\varepsilon_0} \int V \ dV \rho
$$
\n
$$
2EA = \frac{1}{\varepsilon_0} \int V \ dV \rho
$$
\n(4)

\nThe only charge present is 5.89.

The only charge present is σ, so

$$
E = \frac{\sigma}{2\varepsilon_0} \frac{1}{(5)}
$$

When the two triboelectrification layers are in contact, the charge present on their surface are σ_+ and σ_+ , and $\sigma_+ + \sigma_- = \sigma$. Thus, there is an electrical potential (V) when there is a deplanement field (d) between the two triboelectrification layers:

$$
V = \frac{\sigma}{\varepsilon_0} d \tag{6}
$$

After introducing the charge trapping effect, the optimized electrical potential results from the increased dielectric constant can be expressed as:

$$
V = \frac{\sigma'}{\varepsilon_0 \varepsilon_r} d \tag{7}
$$

Where σ' and ε_r present the enhanced surface charge density and the dielectric constant

of PI, and the increase of σ outperform the ε_r , then cause the increase surface potential. With the introduction of short-circuiting effect, the electrical potential is the same as equation 7, but it would be reduced to the same level of bottom electrodes due to the extra charge flow once the short-circuiting effect is triggered.

Note S3. Measurement of the charge decay process of HEEH with CT effect

HEEH was first run for 10 minutes at a rotation speed of 150 rpm. After then, the HEEH's operating mode needs to be switched from rotation to contact-separation in order to detect the process of surface charge decay. To replace the top friction layer, another aluminum layer 3*3 cm² attached to the PMMA substrate was employed. To avoid the impact of excess triboelectrification charge, the spacing between two pieces was fixed at 1 mm to 10 mm during the contact-separation procedure. The contactseparation motion frequency was 1 Hz, and the experiment lasted 1000 seconds.

Note S4. Theoretical analysis of the impact of short-circuiting and chargetrapping effects on device output

The design of HEEH can be regarded as a sliding-mode freestanding triboelectric nanogenerator (*1*). The device has inherent capacitive behavior when applying the classical node concept to analyze its working principle. The capacitance of HEEH comprises two parts. First is the parasitic capacitance of two bottom electrodes, which can be neglected to simplify analysis. Second is the serial connection of the capacitance between the top friction layer and electrode 1 (C₁) and the top friction layer and electrode 2 (C_2) . If we set the length of the top layer to *l* and the gap of the two bottom electrodes to *g*, and assume a small region of dk in the top friction layer (the distance of this region to the left edge of the bottom electrode is k) contains the tribo-charges with a density of σ , and correspondingly the charge quantity on bottom electrode 1 and electrode 2 varies in the range of 0 to σ*dk*. The total charges on the two bottom electrodes are:

$$
Q_1 = \sigma \int_0^l \frac{dk}{1 + C_2(k)/C_1(k)}
$$
\n
$$
Q_2 = \sigma \int_0^l \frac{dk}{1 + C_1(k)/C_2(k)}
$$
\n(9)

Where $C_i(k)$ states for the capacitance between the small surface dk and bottom electrode *i.*

Without considering the short-circuiting effect, the transferred charges have a saturation trend as the top friction material (aluminum) moves from exactly the top of electrode 1 to electrode 2. Therefore, the transferred charge quantity Q_{tr1} and opencircuit voltage can be shown as:

$$
Q_{tr1} = \int_{0}^{l} \frac{\sigma dk}{1 + (C_2(k)/C_1(k))_{x = g + l}} - \int_{0}^{l} \frac{\sigma dk}{1 + C_1(k)/C_2(k)_{x = 0}} \tag{10}
$$

 $V_{oc1} = \frac{\sigma x}{\varepsilon}$ (11) $\mathcal E$

The Q_{tr1} and V_{oc1} are equal to the actual transferred charge quantity for our base device with neither charge-trapping nor short-circuiting effects. With the introduction of the charge-trapping effect, the surface charge density σ would be increased, resulting in the enhanced Q_{tr1} and V_{oc1} during measurement.

After introducing the short-circuiting effect, however, the charge on the surface of the top friction layer can redistribute to both the bottom electrodes to keep the same electrical potential level, which will lead to a huge disturbance of the electrostatic field distribution. Nevertheless, the redistribution of charge can barely cause a significant change of V_{oc} due to the total charge quantity for the whole device is constant, and only the period of short-circuiting contact can lead to the same potential state for the friction layer and bottom electrodes, which can be virtually observed as the zero voltage during measurement.

If the top friction layer and one of the bottom electrodes are connected to create the short-circuiting effect, the transferred charge quantity Q_{tr2} between them is:

$$
Q_{tr2} = \int_{0}^{L} \frac{\sigma dk}{1 + C_{x = position of SC effect}}
$$
 (12)

Where \vec{c} indicates the capacitance ratio between two parts (top friction later and one of the bottom electrodes) for creating the short-circuiting effect.

Therefore, the final Q_{tr} after introducing the short-circuiting effect is:

$$
Q_{tr} = \int_{0}^{l} \frac{\sigma dk}{1 + (C_2(k)/C_1(k))_{x = g + l}} - \int_{0}^{l} \frac{\sigma dk}{1 + C_1(k)/C_2(k)_{x = 0}} + \int_{0}^{l} \frac{\sigma dk}{1 + C_{x = position of SC effect}}
$$
(13)

Comparing to Q_{tr1} , when the device is into the short-circuiting effect, the Q_{tr} can be increased due to the extra contribution of charge flow between friction layer and bottom electrodes.

Note S5. Estimations for calculating power density

- 1. If no thickness of acrylic substrate, PCB board, and metal electrode are provided, it is estimated at 3 mm, 1.6 mm, and 0.025 mm, respectively.
- 2. The thickness increment result from polyester fur is 0.03 mm⁷, according to the photograph and schematic.
- 3. The round hole in the middle for assembling the device is considered a part of the overall area/volume.

Note S6. Parameter-setting for circuit simulation

LTspice was used to evaluate circuit functions and component sizing before circuit fabrication. To simulate the circuit performance, a TENG source was fabricated using a sine voltage source module with adjusted parameters of amplitude (370 V), frequency (240 Hz), and series resistance (100 M Ω). The diodes, J-FET switch, capacitors, and resistors are packaged modules in LTspice. Parameters, such as breakdown voltage, forward current rating, capacitance, and resistance, were adjusted for component sizing. The voltage was displayed on the scope module and exported in the workspace of LTspice.

Figure. S1. Schematic illustration of the triboelectrification of base, SC, CT, and CT&SC devices.

Figure. S2. Voltage output of HEEH made of different triboelectric and bottom electrode materials.

Figure. S3. Electrical outputs at different thicknesses of charge trapping layer.

Figure. S4. Working mechanism of HEEH.

Figure. S5. Simulation of HEEH under different states.

Figure. S6. Surface charge decay of the devices with and without the charge trapping layer.

Figure. **S7.** Capacitor charging of base (A), CT (B), SC (C), and CT&SC (D) devices.

Figure. S8. Stability comparison of the devices.

Figure. S9. Relationship between the width and duration of the short circuit contact.

Figure. S10. Photograph of the commercial lithium battery.

Figure. S11. Traditional circuit for capacitor and battery charging.

Figure. S12. Capacitor and battery charging with the traditional circuit design at rotation speed of 300 rpm.

Figure. S14. TEM image of Mn_3O_4 nanoparticles.

Figure. S15. Photograph of the wastewater treatment setup.

Devices Parameters		Base	SC effect	CT effect	SC&CT effects
Origin indices	$6(mC/m^2)$	152	348	280	661
	$P_{\text{eff}}(W/m^2)$	0.34	0.86	1.24	2.9
	$R_{int} (M\Omega)$	90	13	75	13
	Cost (HKD)	4.2	4.21	5.95	5.96
	ρ (%)	91	$78\,$	90	76
Normal ized indices	σ^*	0.23	0.53	0.42	$\mathbf{1}$
	P_{eff}	0.12	0.3	0.43	$\mathbf{1}$
	$\mathbf{R}_{_{\text{int}}}$	0.14	$1\,$	0.17	$\mathbf{1}$
	Cost	$0.7\,$	0.71	0.99	$\mathbf{1}$
	* ρ	$\mathbf{1}$	0.86	0.99	0.83

Table S1. Original and normalized radar chart.

Table S2. Performance comparison with prominent rotary-structured devices.

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